Intel® Server Board S1200V3RPL

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Specifications

Essentials

Status	Launched
Launch Date	Q2'13
EOL Announce	Sunday, October 30, 2016
Last Order	Sunday, April 30, 2017
Last Receipt Attributes	Thursday, August 31, 2017
Limited 3-year Warranty	Yes
Extended Warranty Available for Purchase (Select Countries)	Yes
Additional Extended Warranty Details	Single Processor Board Extended Warranty
# of QPI Links	1
Compatible Product Series	Intel® Xeon® Processor E3-1200 v4 Family
Board Form Factor	uATX
Chassis Form Factor	4U Rack or Pedestal
Socket	LGA1150
Integrated Systems Available	Yes
Integrated BMC with IPMI	IPMI 2.0
Rack-Friendly Board	Yes
Embedded Options Available	Yes
TDP	95 W
Included Items	Intel® Server Board S1200V3RPL with (4) SATA Cables (1) I/O Shield (1) Intel® Server Deployment & Management DVD (1) Attention document and (1) Quick Start User's Guide. Note: the OEM 10 Pack does not ship with included items.
Recommended Customer Price	N/A
Datasheet	Link
Board Chipset	(Intel® DH82C226 PCH)
Description	An entry-level one socket board with Intel® C226 chipsetsupporting one Intel® Xeon® Processor E3-1200 family, 4 UDIMMs at up to 1600MHz and dual integrated Intel® Ethernet Controller. Optional mezzanine connector or Intel® Remote Management Module 4.
Target Market	Small Business/1st Server
Additional Information URL	Link

Memory Specifications

Max Memory Size (dependent on memory type)	32 GB
Memory Types	DDR3L ECC UDIMM 1333/1600
Max # of Memory Channels	2

Related Products

Single-Socket Server Boards
Intel® Server Board S1200RP Family
Products formerly Rainbow Pass

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PCN/MDDS Information

PCN/MDDS Information Not Available

Max Memory Bandwidth	25.6 GB/s
Physical Address Extensions	40-bit
Max # of DIMMs	4
ECC Memory Supported ‡	Yes
DIMM Type	UDIMM

Graphics Specifications

Integrated Graphics ‡	Yes
Graphics Output	VGA
Discrete Graphics	Supported

Expansion Options

PCI Express Revision	3.0
Max # of PCI Express Lanes	16
PCIe x8 Gen 3	1
PCIe x1 Gen 2.x	1
PCIe x4 Gen 2.x	1
PCIe x8 Gen 2.x	1
Connector for Intel® I/O Expansion Module x8 Gen 3	1
Connector for Intel® Integrated RAID Module	1

I/O Specifications

USB Revision	2.0 and 3.0
# of USB Ports	4
Total # of SATA Ports	6
RAID Configuration	Software RAID RST (0,1,10,5) and ESRT2 (0,1,10)
# of Serial Ports	1
# of LAN Ports	2
Integrated LAN	2x 1GbE
Firewire	No
Embedded USB (eUSB) Solid State Drive Option	Yes
Integrated SAS Ports	0
Integrated InfiniBand*	No

Package Specifications

Max CPU Configuration	1
Low Halogen Options Available	See MDDS

Advanced Technologies

Intel® Virtualization Technology for Directed I/O (VT-d) ‡	Yes
Intel® Remote Management Module Support	Yes
Intel® Node Manager	Yes
Intel® Quick Resume Technology	No
Intel® Quiet System Technology	No
Intel® HD Audio Technology	No
Intel® Matrix Storage Technology	No
Intel® Rapid Storage Technology	No
Intel® Rapid Storage Technology enterprise	Yes
Intel® Fast Memory Access	Yes
Intel® Flex Memory Access	No

Intel® I/O Acceleration Technology	Yes
Intel® Advanced Management Technology	Yes
Intel® Server Customization Technology	No
Intel® Build Assurance Technology	No
Intel® Efficient Power Technology	No
Intel® Quiet Thermal Technology	No

Intel® Data Protection Technology

Intel® AES New Instructions	Yes

Intel® Platform Protection Technology

Trusted Execution Technology ‡	Yes

Intel® Transparent Supply Chain

TPM Version	1.2

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Refer to Datasheet for formal definitions of product properties and features.

“Announced” SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

“Conflict free” and “conflict-free” means “DRC conflict free”, which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals (tin, tantalum, tungsten and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo (DRC) or adjoining countries. Intel also uses the term "conflict-free" in a broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel processors manufactured before January 1, 2013 are not confirmed conflict free. The conflict free designation refers only to product manufactured after that date. For Intel Boxed Processors, the conflict free designation refers to the processor only, not to any additional included accessories, such as heatsinks/coolers.

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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

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